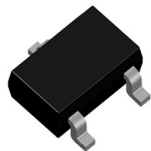


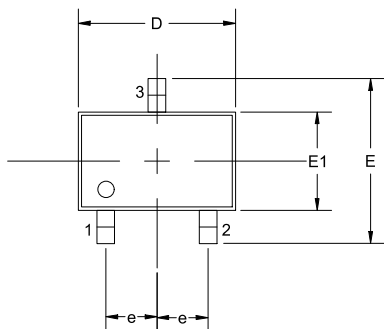
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

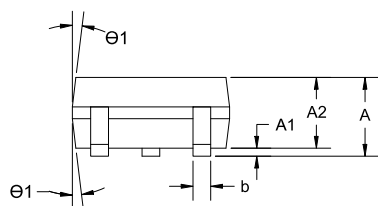


SC-70, 3 Lead, 1.25x2
CASE 419AB
ISSUE A

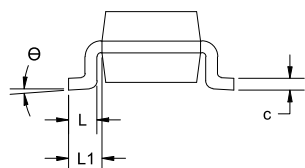
DATE 13 FEB 2023



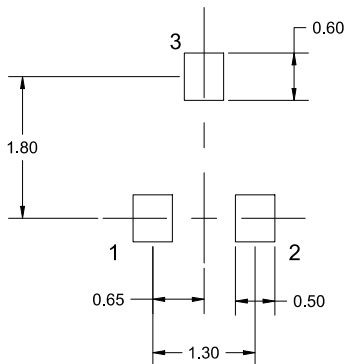
TOP VIEW



SIDE VIEW



END VIEW



SOLDERING FOOTPRINT

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES IN DEGREES.
2. COMPLIES WITH JEDEC MO-203

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80		1.10
A1	0.00		0.10
A2	0.80	0.90	1.00
b	0.15		0.30
c	0.08		0.22
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.26	0.36	0.46
L1	0.42 REF		
θ	0°		8°
θ1	4°		10°

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON34256E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SC-70, 3 LEAD, 1.25X2	PAGE 1 OF 1

onsemi and ONsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.